In the Claims

The following Listing of Claims replaces all prior versions in the application:

LISTING OF CLAIMS

1-20 (Cancelled)

21. (Currently Amended) A Device for the metered delivery of a viscous liquid, comprising:

a first and second piston consisting of a selected one of hard metal or tool steel,

a pump body comprising a first sleeve consisting of a selected one of hard metal or ceramic and having a first drill hole accommodating the pistons as well as two further drill holes which run orthogonally to the first drill hole and one end of which opens out into the first drill hole and the other end of which opens out into an intake chamber or a discharge chamber in the pump body, wherein the first drill hole and the first and second piston each form a slot seal and wherein the pistons each stick out at a respective end of the first drill hole, and

a drive mechanism for moving the pistons back and forth such that a width of a slit formed between the pistons varies during the back and forth movement.

22. (Currently Amended) The device according to claim 21, the pump body further including two blind holes, wherein the ends of the first drill hole of the first sleeve open out into the blind holes.

23. (Previously Presented) The device according to claim 21, wherein the first sleeve and the pump body consist of one piece of material.

24. (Previously Presented) The device according to claim 22, wherein the first sleeve and the pump body consist of one piece of material.

25. (Previously Presented) The device according to claim 21, the pump body further comprising two bearings in each of which a second or third sleeve, respectively, is movably supported, whereby an end of the first piston is secured in the second sleeve and an end of the second piston is secured in the third sleeve, the second and third sleeve forming part of the drive mechanism.

26. (Previously Presented) The device according to claim 22, the pump body further comprising two bearings in each of which a second or third sleeve, respectively, is movably supported, whereby an end of the first piston is secured in the second sleeve and an end of the second piston is secured in the third sleeve, the second and third sleeve forming part of the drive mechanism.

27. (Previously Presented) The device according to claim 21, wherein a radius of the first drill hole is manufactured within a tolerance of $\pm$ 0.5 μm and a radius of the pistons with a tolerance of $\pm$ 0.15 μm.

28. (Previously Presented) The device according to claim 22, wherein a radius of the first drill hole is manufactured within a tolerance of $\pm$ 0.5 μm and a radius of the pistons with a

tolerance of ± 0.15 μm.

29. (Previously Presented) The device according to claim 23, wherein a radius of the first drill hole is manufactured within a tolerance of ± 0.5 μm and a radius of the pistons with a tolerance of ± 0.15 μm.

30. (Previously Presented) The device according to claim 24, wherein a radius of the first drill hole is manufactured within a tolerance of ± 0.5 μm and a radius of the pistons with a tolerance of ± 0.15 μm.

31. (Previously Presented) The device according to claim 25, wherein a radius of the first drill hole is manufactured within a tolerance of ± 0.5 μm and a radius of the pistons with a tolerance of ± 0.15 μm.

32. (Previously Presented) Use of the device according to claim 21 on a writing head for the application of adhesive onto a substrate which is to be equipped with a semiconductor chip.

33. (Previously Presented) Use of the device according to claim 22 on a writing head for the application of adhesive onto a substrate which is to be equipped with a semiconductor chip.

34. (Previously Presented) Use of the device according to claim 23 on a writing head for the application of adhesive onto a substrate which is to be equipped with a semiconductor

chip.

35. (Previously Presented) Use of the device according to claim 24 on a writing head for the application of adhesive onto a substrate which is to be equipped with a semiconductor chip.

36. (Previously Presented) Use of the device according to claim 25 on a writing head for the application of adhesive onto a substrate which is to be equipped with a semiconductor chip.

37. (Previously Presented) Use of the device according to claim 26 on a writing head for the application of adhesive onto a substrate which is to be equipped with a semiconductor chip.

38. (Previously Presented) Use of the device according to claim 27 on a writing head for the application of adhesive onto a substrate which is to be equipped with a semiconductor chip.

39. (Previously Presented) Use of the device according to claim 28 on a writing head for the application of adhesive onto a substrate which is to be equipped with a semiconductor chip.

40. (Previously Presented) Use of the device according to claim 29 on a writing head for the application of adhesive onto a substrate which is to be equipped with a semiconductor chip.